Schottky Barrier Diode

DB2W40900L

Panasonic

DB2W40900L

Silicon epitaxial planar type

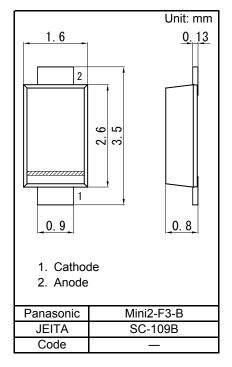
For high frequency rectification DB2X415 in Mini2 clip type package

■ Features

- · Low forward voltage VF
- Forward current (Average) IF(AV) = 3 A rectification is possible
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol: AB

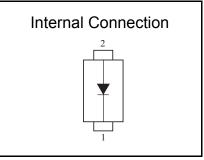
■ Packaging

Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)



Parameter	Symbol	Rating	Unit
Reverse voltage	VR	40	V
Forward current (Average) *1	IF(AV)	3	Α
Non-repetitive peak forward surge current *2	IFSM	30	Α
Junction temperature *1	Tj	150	°C
Operating ambient temperature	Topr	-40 to +85	°C
Storage temperature	Tstg	-55 to +150	°C
11 4 TI 00 00	•		•

Note: *1 TI = 80 °C



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^{*2 50} Hz sine wave 1 cycle (Non-repetitive peak current)

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Revision. 3

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■ Electrical Characteristics Ta = 25 °C ± 3 °C

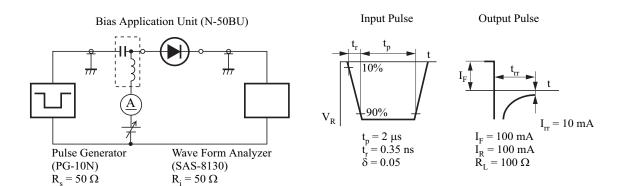
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	VF1	IF = 1.0 A			0.44	V
	VF2	IF = 3.0 A			0.55	
Reverse current	IR	VR = 40 V			200	μA
Terminal capacitance	Ct	VR = 10 V, f = 1 MHz		70		pF
Reverse recovery time *1 tri	trr	IF = IR = 100 mA		25		ns
	u I	Irr = 10 mA, RL = 100 Ω				

- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.
 - 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
 - 3. *1 trr test circuit

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: 2013-04-27

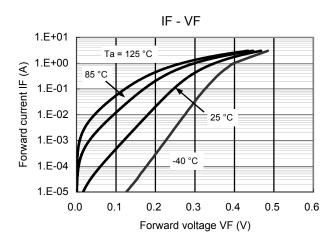
Revised

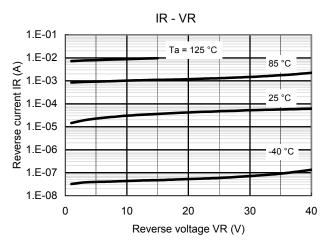


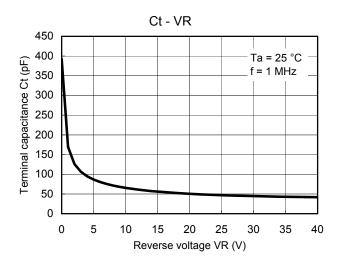
Panasonic

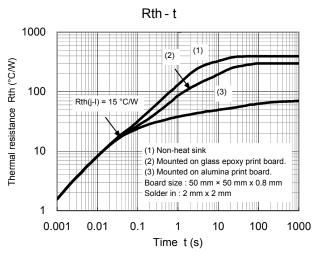
Schottky Barrier Diode DB2W40900L

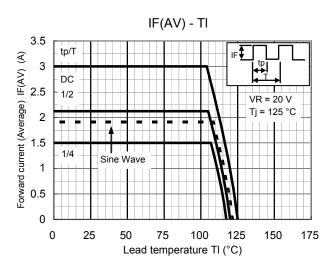
Technical Data (reference)

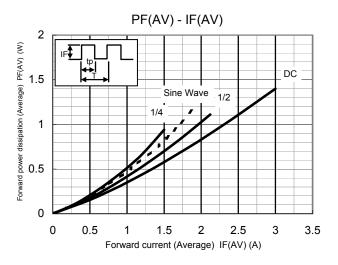












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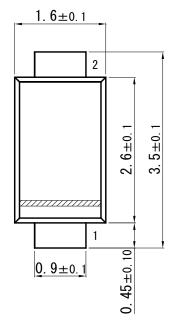
Schottky Barrier Diode

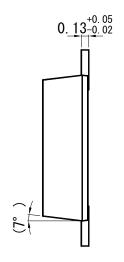
DB2W40900L

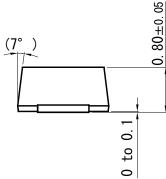
Panasonic

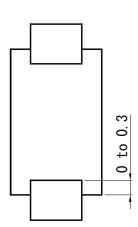
Mini2-F3-B

Unit: mm

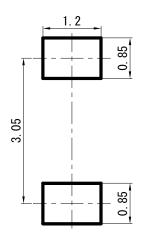








■ Land Pattern (Reference) (Unit: mm)



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